



HIRP1608Q06-B30

SMD Type 850nm Infrared Emitter

Features

- Small double-end package
- Viewing Angle = $\pm 65^\circ$
- High reliability
- Good spectral matching to Si photo detector
- RoHS compliance

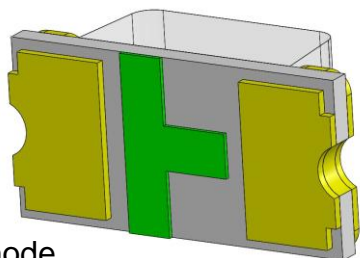
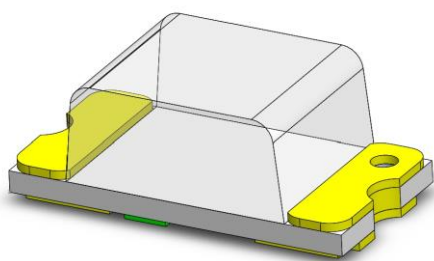
Applications

- Infrared sensor

Description

The HIRP1608Q06-B30 is a GaAlAs infrared LED housed in a miniature SMD package. The device has a peak wavelength of 850nm LED spectrally matched with phototransistor or photodiode.

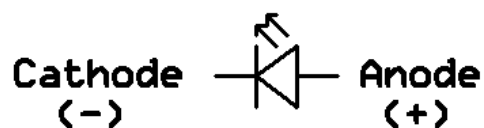
Package Outline



Cathode

Anode

Schematic



**HIRP1608Q06-B30****SMD Type 850nm Infrared Emitter****Absolute Maximum Rating at 25°C**

Symbol	Parameters	Ratings	Units	Notes
I _F	Continuous Forward Current	70	mA	
I _{FP}	Peak Forward Current	0.7	A	1
V _R	Reverse Voltage	5	V	
T _{opr}	Operating Temperature	-40 ~ +85	°C	
T _{stg}	Storage Temperature	-40 ~ +100	°C	
T _{sol}	Soldering Temperature	260	°C	2
P _D	Power Dissipation at(or below) 25°C Free Air Temperature	140	mW	

Electro-Optical Characteristics *TA = 25°C (unless otherwise specified)***Optical Characteristics**

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
I _e	Radiant Intensity	I _F =20mA	1.3	1.8	-	mW/sr	
		I _F =70mA	-	6.0	-		
λ _p	Peak Wavelength	I _F =20mA	-	850	-	nm	
Δλ	Spectral Bandwidth	I _F =20mA	-	30	-	nm	
θ _{1/2}	Angle of Half Intensity	I _F =20mA	-	±65	-	deg	

Electrical Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
V _F	Forward Voltage	I _F =20mA	1.30	1.40	1.7	V	
		I _F =70mA	1.40	1.60	2.0		
I _R	Reverse Current	V _R =5V	-	-	10	μA	

Notes:

1. I_{FP} Conditions--Pulse Width ≤ 100μs and Duty ≤ 1%.
2. Soldering time ≤ 5 seconds.



Typical Characteristic Curves

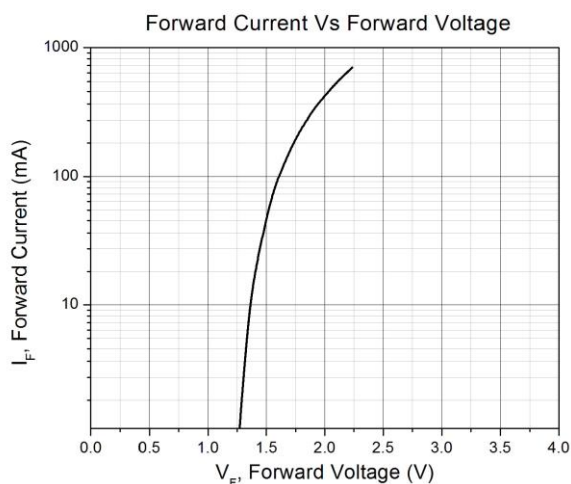


Figure 1

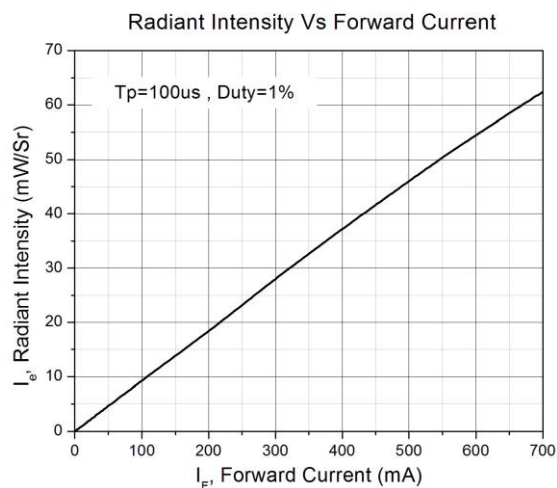


Figure 2

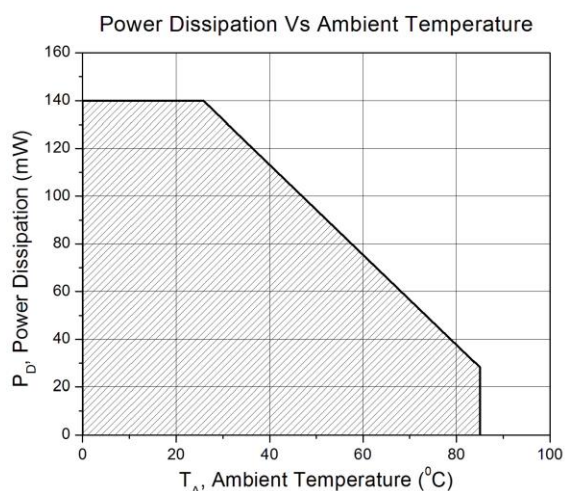


Figure 3

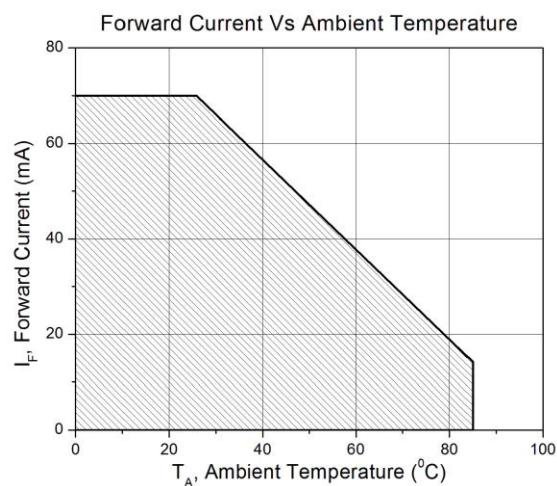


Figure 4

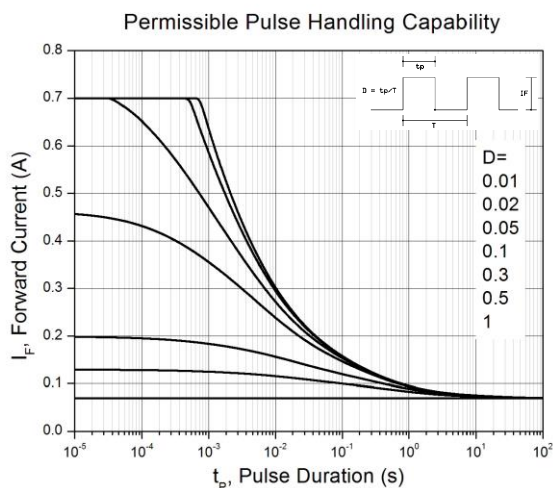


Figure 5

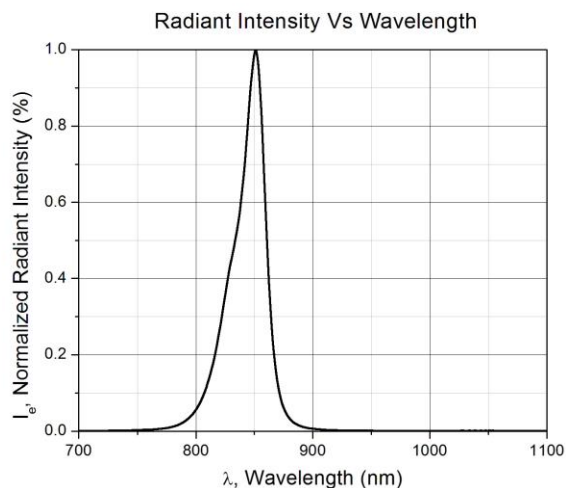


Figure 6



Typical Characteristic Curves

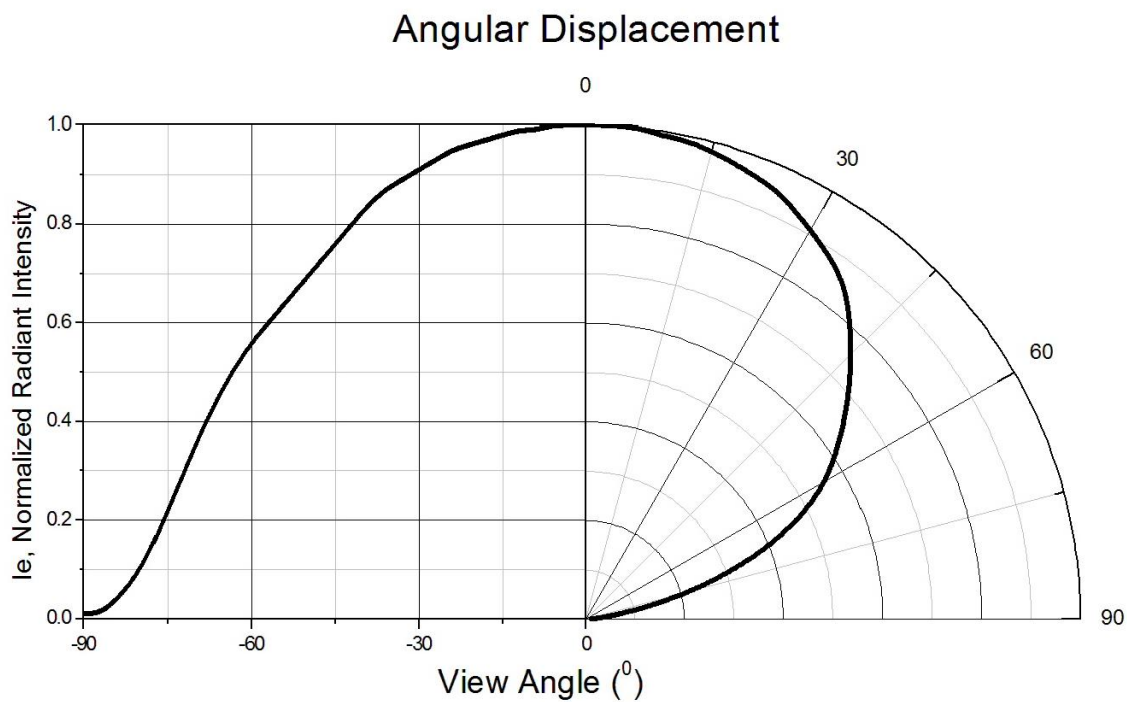


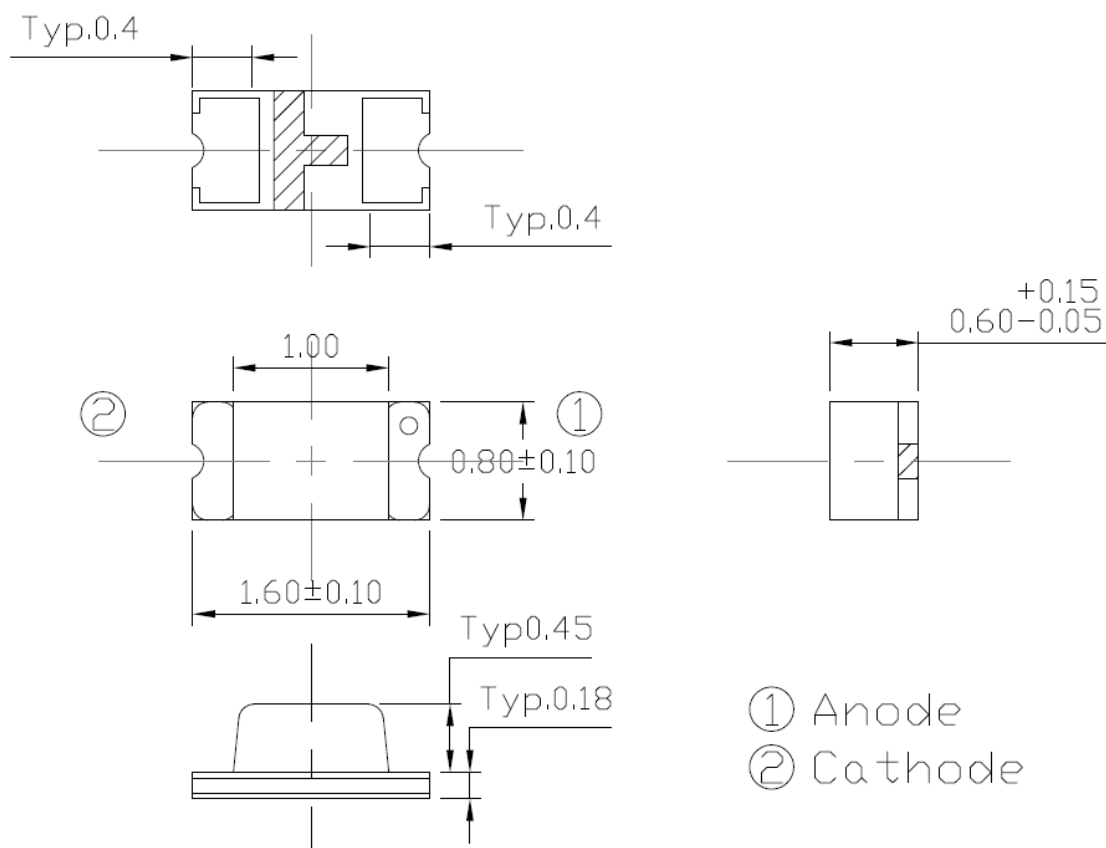
Figure 7



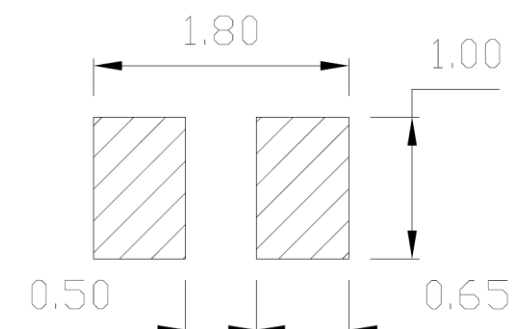
HIRP1608Q06-B30

SMD Type 850nm Infrared Emitter

Package Dimension *All dimensions are in mm, unless otherwise stated*



Recommended Soldering Mask *All dimensions are in mm, unless otherwise stated*



Ordering Information

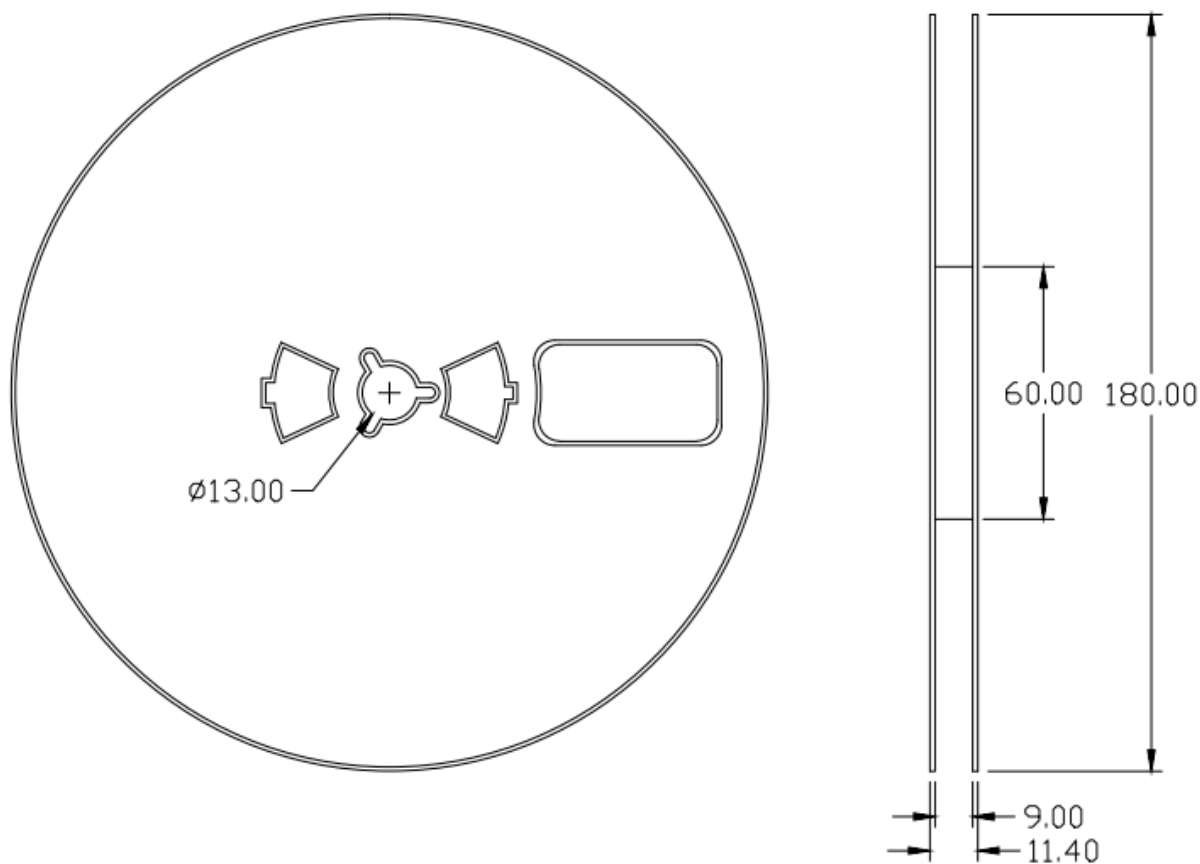
Part Number	Description	Quantity
HIRP1608Q06-B30	Tape & Reel	4000 pcs



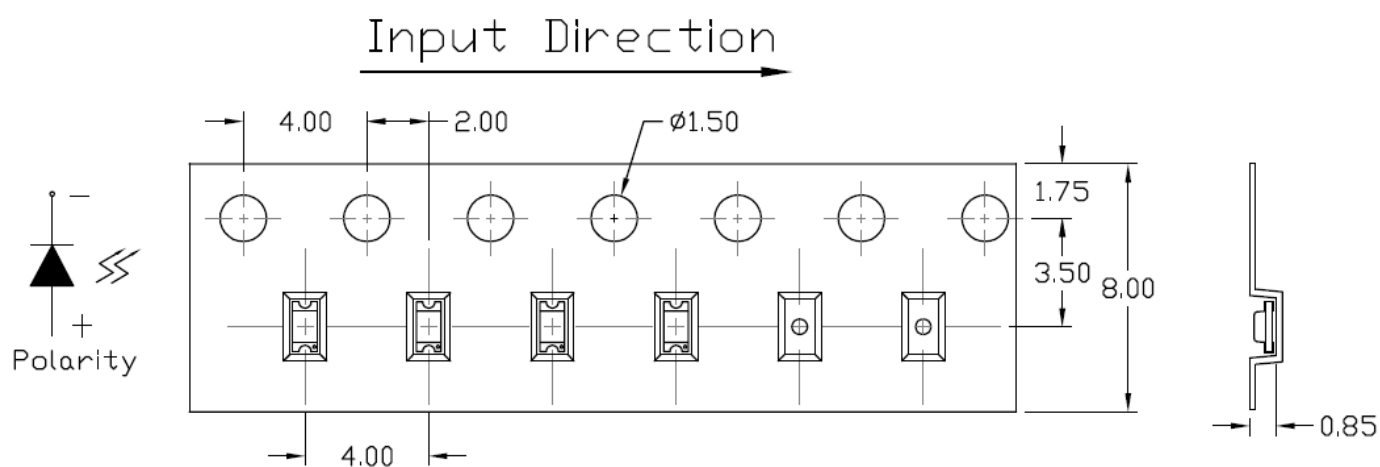
HIRP1608Q06-B30

SMD Type 850nm Infrared Emitter

Reel Dimension *All dimensions are in mm, unless otherwise stated*



Tape Dimension *All dimensions are in mm, unless otherwise stated*





HIRP1608Q06-B30

SMD Type 850nm Infrared Emitter

Label Form Specification

CT Micro
International Corporation

MADE IN CHINA

Part no.: XXXXXXXXX
Serial no.: XX000XX
Lot no.: XXXXXXXXX
Q'ty: XXXX pcs
Date Code: 20XXXXX

Bin Code: X

RoHS
Pb-free

Part no: CTM Production Number

Serial no: Production Number

Lot no: Lot number

Q'ty: Packing Quantity

Date Code: Manufacture Date

Bin Code: 1e Ranks

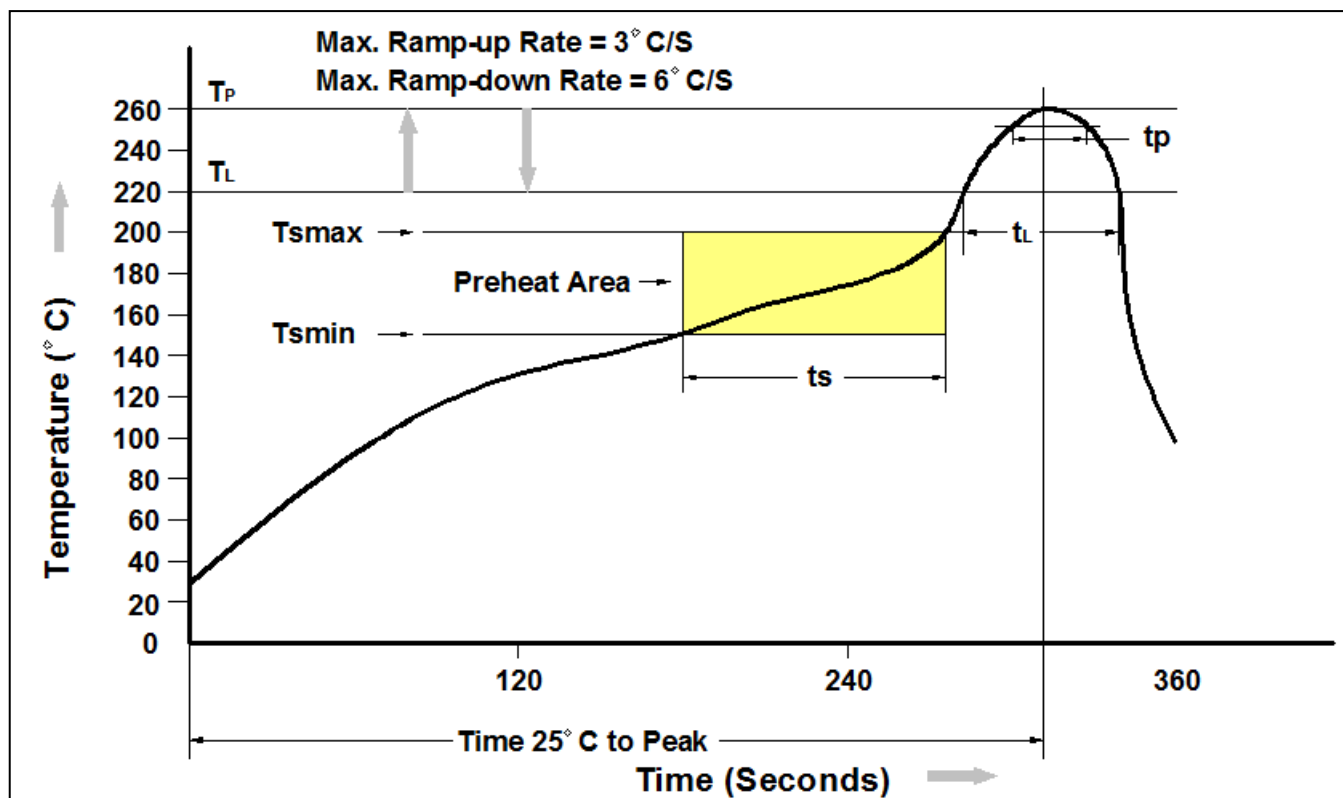
MADE IN CHINA: Production Place

Storage Condition

1. Do not open moisture proof bag before the products are ready to use.
2. The moisture barrier bag should be stored at 30°C and 90%R.H. max. before opening.
Shelf life of non-opened bag is 12 months after the bag sealing date.
3. After opening the moisture barrier bag floor life is 168h at 30°C/60%RH. max. Unused LEDs should be resealed into moisture barrier bag. (Refer to J-STD-020 Standard)
4. If the moisture absorbent material has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the J-STD-033 Standard conditions.



Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tssmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tssmin to Tsmax)	60-120 seconds
Ramp-up Rate (tL to tp)	3°C/second max.
Liquidous Temperature (TL)	217°C
Time (tL) Maintained Above (TL)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (tp) within 5°C of 260°C	30 seconds
Ramp-down Rate (TP to TL)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.*